

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2973573

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YANG WEI	10/12/2011
SHOU-SHAN FAN	10/12/2011
RECEIVING PARTY DATA	
Name:	Tsinghua University
Street Address:	No.1,Qinghua Yuan,Haidian District
City:	Beijing
State/Country:	CHINA
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66, Chung Shan Road, Tu-Cheng Dist.
City:	New Taipei
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14098775
CORRESPONDENCE DATA	
Fax Number:	(713)456-2836
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7135713400
Email:	eoabcd@scienbizip.com, eoaproce@scienbizip.com, sbp@novakdruce.com
Correspondent Name:	ZHIGANG MA
Address Line 1:	1000 LOUISIANA STREET, FIFTY-THIRD FLOOR
Address Line 4:	HOUSTON, TEXAS 77002
ATTORNEY DOCKET NUMBER:	US54621
NAME OF SUBMITTER:	ZHIGANG MA
SIGNATURE:	/Zhigang Ma/
DATE SIGNED:	08/08/2014
Total Attachments: 2	
source=US54621111012ASM#page1.tif	
source=US54621111012ASM#page2.tif	

PATENT

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. YANG WEI, residing at Beijing, China
2. SHOU-SHAN FAN, residing at Beijing, China
3. _____, residing at _____
4. _____, residing at _____
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____
8. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **TSINGHUA UNIVERSITY** having a principal place of business at **No.1, Qinghua Yuan, Haidian District, Beijing City, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66, Chung Shan Road, Tu-Cheng Dist., New Taipei City, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **METHOD FOR MAKING SEMICONDUCTOR EPITAXIAL STRUCTURE** for which the undersigned

☐ previously executed --- Ser. No. _____ and filing date of _____

☒ is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Yang Wei</u> YANG WEI	<u>Oct.12,2011</u> Date
2.	<u>Shou-Shan Fan</u> SHOU-SHAN FAN	<u>Oct.12,2011</u> Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date